SN74LVC652 OCTAL BUS TRANSCEIVER AND REGISTER WITH 3-STATE OUTPUTS

DB. DW. OR PW PACKAGE

SCAS303A - JANUARY 1993 - REVISED JULY 1995

- EPIC[™] (Enhanced-Performance Implanted CMOS) Submicron Process
- Typical V_{OLP} (Output Ground Bounce)
 < 0.8 V at V_{CC} = 3.3 V, T_A = 25°C
- Typical V_{OHV} (Output V_{OH} Undershoot)
 2 V at V_{CC} = 3.3 V, T_A = 25°C
- Latch-Up Performance Exceeds 250 mA Per JEDEC Standard JESD-17
- Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages

(TOP VIEW) 24 🛮 V_{CC} CLKAB [SAB 2 23 CLKBA OEAB [] 3 22 SBA 21 OEBA A1 🏻 4 A2 📙 5 20 B1 АЗ 6 19 B2 18 B3 A4 Α5 17 B4 II B5 A6 16 15 B6 Α7 10 14 B7 Α8 II 11 **GND** 13 J B8

description

This octal bus transceiver and register is designed for 2.7-V to 3.6-V V_{CC} operation.

The SN74LVC652 consists of bus transceiver circuits, D-type flip-flops, and control circuitry arranged for multiplexed transmission of data directly from the data bus or from the internal storage registers.

Output-enable (OEAB and OEBA) inputs are provided to control the transceiver functions. Select-control (SAB and SBA) inputs are provided to select whether real-time or stored data is transferred. The circuitry used for select control eliminates the typical decoding glitch that occurs in a multiplexer during the transition between stored and real-time data. A low input selects real-time data, and a high input selects stored data. Figure 1 illustrates the four fundamental bus-management functions that can be performed with the SN74LVC652.

Data on the A or B data bus, or both, can be stored in the internal D-type flip-flops by low-to-high transitions at the appropriate clock (CLKAB or CLKBA) inputs regardless of the select- or enable-control pins. When SAB and SBA are in the real-time transfer mode, it is possible to store data without using the internal D-type flip-flops by simultaneously enabling OEAB and OEBA. In this configuration, each output reinforces its input. When all other data sources to the two sets of bus lines are at high impedance, each set of bus lines remains at its last state.

To ensure the high-impedance state during power up or power down, $\overline{\text{OEBA}}$ should be tied to V_{CC} through a pullup resistor and OEAB should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sinking/current-sourcing capability of the driver.

The SN74LVC652 is characterized for operation from -40°C to 85°C.



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FUNCTION TABLE

INPUTS					DATA I/O†		OPERATION OR FUNCTION		
OEAB	OEBA	CLKAB	CLKBA	SAB	SBA	A1 THRU A8	B1 THRU B8	OPERATION OR FUNCTION	
L	Н	H or L	H or L	Х	Х	Input	Input	Isolation	
L	Н	\uparrow	\uparrow	X	X	Input	Input	Store A and B data	
Х	Н	\uparrow	H or L	X	X	Input	Unspecified [‡]	Store A, hold B	
Н	Н	\uparrow	\uparrow	X [‡]	X	Input	Output	Store A in both registers	
L	X	H or L	\uparrow	X	X	Unspecified [‡]	Input	Hold A, store B	
L	L	\uparrow	\uparrow	X	X‡	Output	Input	Store B in both registers	
L	L	Χ	Χ	X	L	Output	Input	Real-time B data to A bus	
L	L	Χ	H or L	X	Н	Output	Input	Stored B data to A bus	
Н	Н	Χ	Χ	L	X	Input	Output	Real-time A data to B bus	
Н	Н	H or L	Χ	Н	X	Input	Output	Stored A data to B bus	
н	L	H or L	H or L	Н	Н	Output	Output	Stored A data to B bus and stored B data to A bus	

[†] The data output functions may be enabled or disabled by a variety of level combinations at the OEAB or OEBA inputs. Data input functions are always enabled; i.e., data at the bus pins is stored on every low-to-high transition on the clock inputs.



[‡] Select control = L; clocks can occur simultaneously.

Select control = H; clocks must be staggered in order to load both registers.

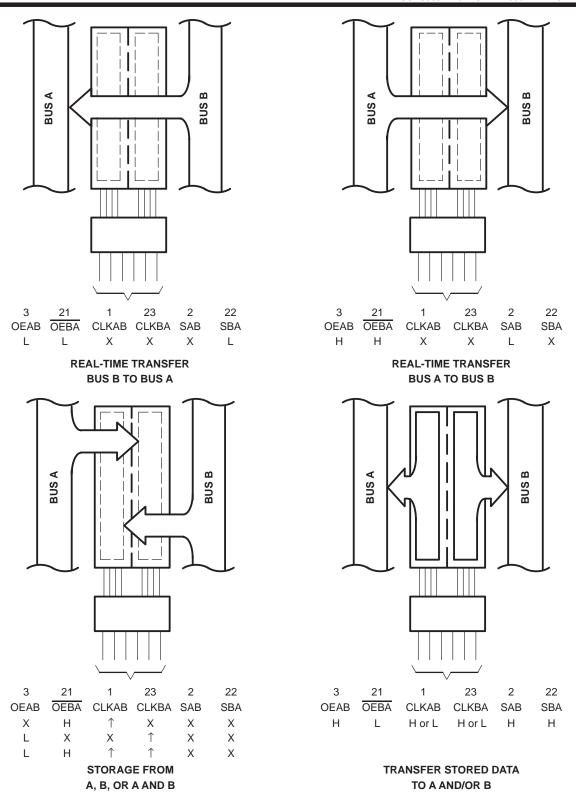
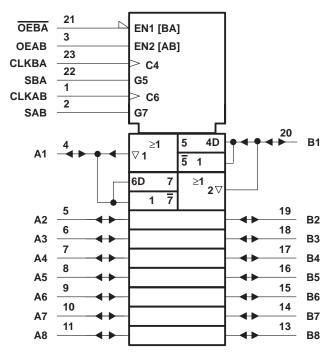


Figure 1. Bus-Management Functions



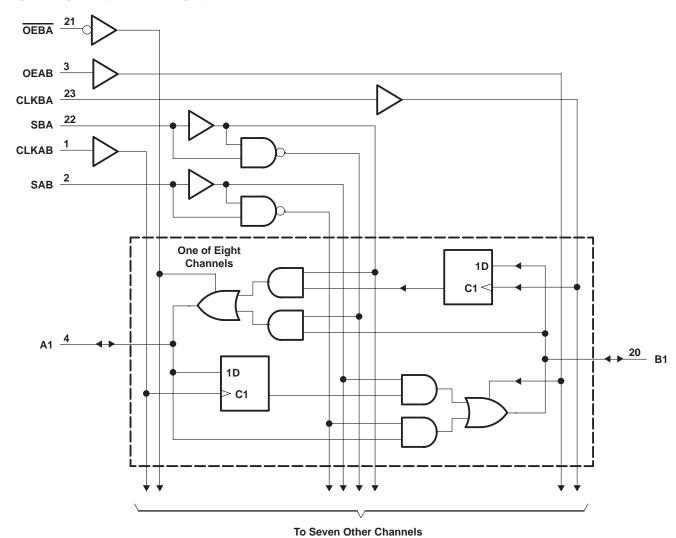
logic symbol[†]



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



logic diagram (positive logic)





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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	0.5 V to 4.6 V
Input voltage range, V _I : Except I/O ports (see Note 1)	
I/O ports (see Notes 1 and 2)	$-0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Output voltage range, VO (see Notes 1 and 2)	$-0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Input clamp current, $I_{ K }(V_{ } < 0)$	–50 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$)	±50 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±50 mA
Continuous current through V _{CC} or GND	±100 mA
Maximum power dissipation at $T_A = 55^{\circ}$ C (in still air) (see Note 3): DB package	0.65 W
DW package	1.7 W
PW package	0.7 W
Storage temperature range, T _{stg}	65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
 - 2. This value is limited to 4.6 V maximum.
 - 3. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the *Package Thermal Considerations* application note in the 1994 *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002B.

recommended operating conditions (see Note 4)

			MIN	MAX	UNIT	
V	Cumply yeltogo	Operating	2	3.6	V	
VCC	Supply voltage	Data retention only	1.5		V	
V _{IH}	High-level input voltage	$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	2		V	
V _{IL}	Low-level input voltage	$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$		0.8	V	
V	Control inp		0	5.5	V	
VI	Input voltage	Data inputs	0	VCC	V	
٧o	Output voltage		0	VCC	V	
1	High-level output current	V _{CC} = 2.7 V		-12	mA	
IOH	High-level output current	V _{CC} = 3 V		-24	IIIA	
la.	Lough subsuit ourrent	V _{CC} = 2.7 V		12	A	
IOL	Low-level output current	V _{CC} = 3 V		24	mA	
$\Delta t/\Delta v$	Input transition rise or fall rate		0	10	ns/V	
TA	Operating free-air temperature		-40	85	°C	
			•			

NOTE 4: Unused inputs must be held high or low to prevent them from floating.



electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PA	RAMETER	TEST CONDITIONS	v _{cc} †	MIN TYP	МАХ	UNIT
		$I_{OH} = -100 \mu\text{A}$	MIN to MAX	V _{CC} -0.2		
\ _{\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\}		I _{OH} = – 12 mA	2.7 V	2.2		V
VOH		10H = - 12 IIIA	3 V	2.4		V
		$I_{OH} = -24 \text{ mA}$	3 V	2		
		$I_{OL} = 100 \mu\text{A}$	MIN to MAX		0.2	
VOL		I _{OL} = 12 mA	2.7 V		0.4	V
		I _{OL} = 24 mA	3 V		0.55	
lį		$V_I = 5.5 \text{ V or GND}$	3.6 V		±5	μΑ
I _{OZ} §		$V_O = V_{CC}$ or GND	3.6 V		±10	μΑ
Icc	2	$V_I = V_{CC}$ or GND, $I_O = 0$	3.6 V		20	μΑ
∆lcc		One input at V _{CC} – 0.6 V, Other inputs at V _{CC} or GND	3 V to 3.6 V		500	μΑ
Ci	Control inputs	$V_I = V_{CC}$ or GND	3.3 V	4.0	3	pF
C _{io}	A or B ports	$V_O = V_{CC}$ or GND	3.3 V	7.5	2	pF

[†] For conditions shown as MIN or MAX, use the appropriate values under recommended operating conditions.

timing characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 2)

		V _{CC} = 3.3 V ± 0.3 V		V _{CC} = 2.7 V		UNIT
		MIN	MAX	MIN	MAX	
fclock	Clock frequency	0	100	0	80	MHz
t _W	Pulse duration	5		5		ns
t _{su}	Setup time, data before CLK↑	5		5		ns
th	Hold time, data after CLK↑	1		1		ns

switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 2)

PARAMETER	FROM	l l	V _{CC} = 3.3 V ± 0.3 V		V _{CC} = 2.7 V		UNIT
	(INPUT)		MIN	MAX	MIN	MAX	
f _{max}			100		80		MHz
	A or B	B or A	1.5	8		9.2	
t _{pd}	CLK	A or B	1.5	9		11	ns
	SAB or SBA	A or B	1.5	9		11	
t _{en}	ŌĒ	A or B	1.5	8.5		9.5	ns
^t dis	ŌĒ	A or B	1.5	8.5		9.5	ns
t _{en}	OE	A or B	1.5	9		10	ns
^t dis	OE	A or B	1.5	9		10	ns



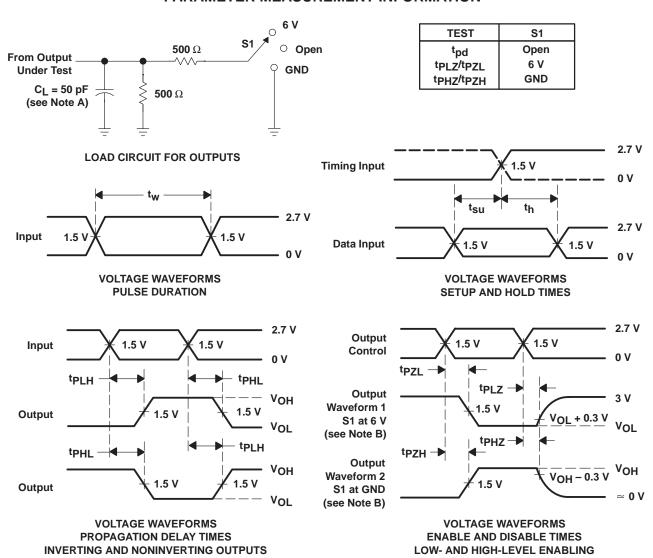
[‡] All typical values are measured at $V_{CC} = 3.3 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

[§] For I/O ports, the parameter IOZ includes the input leakage current.

operating characteristics, V_{CC} = 3.3 V, T_A = 25°C

PARAMETER			TEST CONDITIONS	TYP	UNIT
C _{pd}	Power dissipation capacitance per transceiver	Outputs enabled	C 50 pE f _ 10 MHz	38	nF
		Outputs disabled	$C_L = 50 \text{ pF}, f = 10 \text{ MHz}$	4.2	PΓ

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_I includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, $t_r \leq 2.5$ ns, $t_f \leq 2.5$ ns.
- The outputs are measured one at a time with one transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.

Figure 2. Load Circuit and Voltage Waveforms



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